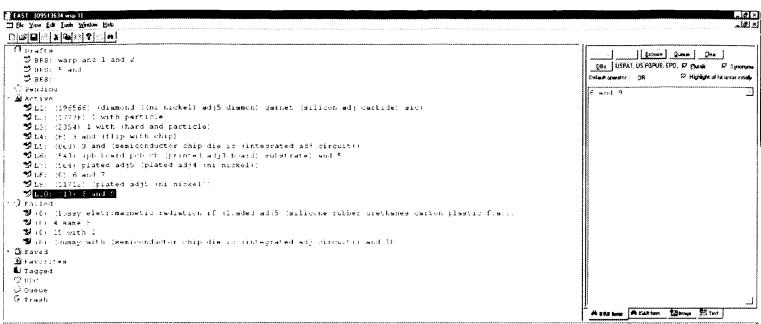
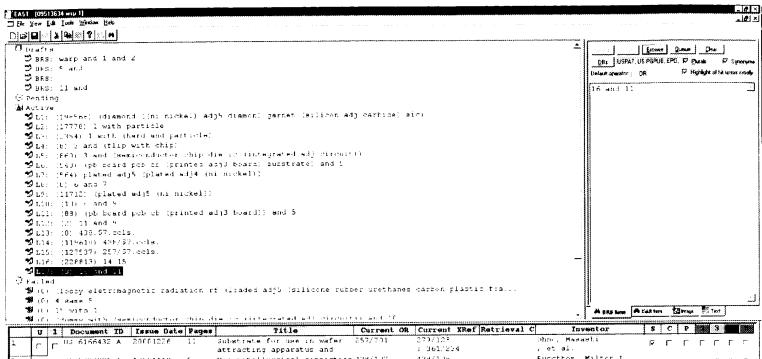


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1	۲		มส์ 2001003 Al	1345			Laminated radiation member, power semiconductor			Araki, Kiyoshi , Kada, Masahiro	Æ	٢	r	Γ	Г	
2	_	Γ	US 6103874	В1	20010206		Substrate material for mounting a semiconductor	428 472	428/323 ; 428/305	Yamagata, Shinichi , + el.	Ø	٢	٢	Γ	רו	
3	۳.	t	03 6117493	A	20000912		Micro texture media made by polishing of a selectively	427 '5 33	427/125 : 427/130	Wong, Javier , et al.	j:	٢	1	ſ"	r i	t.
4	г	Г	US 6054103	A	20000425		Method for making CVD diamond coated substrate for	427, 249, 0	427 122 : 437/249:11	Zimmer, Jerry W.	F	Γ	г	۲	Г (ГГ
\$	٣	٢	US 5930722	A	19991109		Flated aluminum alloy, cylinder block thereof,	205/213	205/640	Kuroda, Tetsuya , et al.	Þ	٢	r	۲	r 1	
5	,	٢	us 5921856	A	19990713		CVD diamond coated substrate for polishing pad	451/539	451/526	Zimmer, Jerry W.	Þ	r	r	٣	r i	-
7	г	Γ	us 5759667	A	19980602		Diamond wire drawing die and process for manufacturing	428, 132	420 131 ; 408/212	Takahashi, Teshiya , et al.	₽	٢	Γ	۲	۳ ۱	- r.
8	١,	٢	បន 5571236	A	19961105	9	Diamond wire drawing die	72/467	•	Takahashi, Toshiya , et al.	F	Г	ſ	٢	Γ 1	- r
ÿ	г	Γ	U\$ 52757⊎2	A	19931228		Coated parts with film having powder-skeleton	427, 242	235.83 : 407/11	Sagawa, Masato , et el.	F	٢	٢	Γ	ר ו	
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1	r	Γ'	13 6166432	A	2000123 <i>6</i>		Substrate for use in wafer attracting apparatus and	257/701	279/125 : 361/234	Ohne, Masashi , et al.	F	Γ	٢	רו	Г	г
2	-	์ ୮ '	18 5834335	A	1#961110		Non-metallurgical connection between an integrated	438/137	438/109 : 438/109	Euschbom, Milton L.	₽	٢	٢	Г 1	- r	۲
3		r '	J3 4 979019	A	19901218	_	Frinted circuit board with inorganic insulating matrix	257/747	174/258 ; 174/35R	Paquette, Edward L., , et al.	Þ	٣	r	t	1	r
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